

High-Speed USB 2.0 (480-Mbps) 1:2 Multiplexer/Demultiplexer Switch

FEATURES

-3dB Bandwidth: 550MHzSupply Range: +1.8V to +5.5V

• R_{ON} is Typically 6Ω

• Fast Switching Times:

t_{ON} 20ns t_{OFF} 15ns

Break-Before-Make Switching

Low Power Consumption (1μA Maximum)

• Rail-to-Rail Input and Output Operation

Extended Industrial Temperature Range:
 -40°C to +85°C

 Micro SIZE PACKAGES: MSOP-10, QFN-1.4×1.8-10L

APPLICATIONS

- Routes Signals for USB 1.0, 1.1, and 2.0
- MP3 and Other Personal Media Players
- Portable Instrumentation
- USB Switching
- Digital Cameras
- Set-Top Box
- Cell Phones
- PDAs

DESCRIPTION

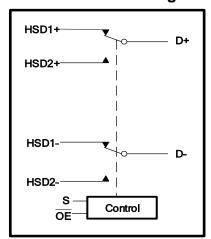
The RS2227 is a high-speed, low-power double-pole/double-throw (DPDT) analog switch with single Enable. It is designed to operate from 1.8 V to 5.5 V.

The RS2227 has a bus-switch enable pin, \overline{OE} , that can place the signal paths in high impedance. This allows the user to isolate the bus when it is not in use and consume less current

The RS2227 is a high-bandwidth switch specially designed for the switching of high-speed USB2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os.

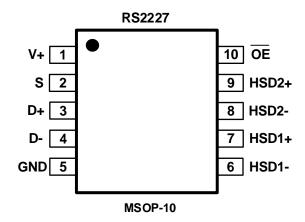
The RS2227 is available MSOP-10 and QFN-1.4 \times 1.8-10L package. It operates over an ambient temperature range of -40 $^{\circ}$ C to +85 $^{\circ}$ C.

Functional Block Diagram





PIN CONFIGURATIONS



PIN DESCRIPTION

NAME	PIN	FUNCTION
V+	1	Power Supply
GND	5	Ground
S	2	Select Input
ŌE	10	Output Enable
HSD1+, HSD2+	7,9	
HSD1-, HSD2-	6,8	Data Port
D+, D-	3,4	

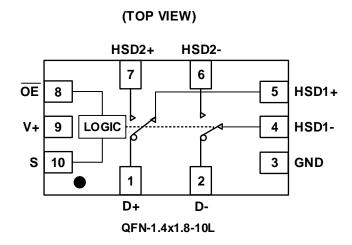
FUNCTION TABLE

ŌĒ	S	HSD1+, HSD1-	HSD2+, HSD2-
0	0	ON	OFF
0	1	OFF	ON
1	Х	OFF	OFF

X =Don't care



PIN CONFIGURATIONS



PIN DESCRIPTION

NAME	PIN	FUNCTION	
V+	9	Power Supply	
GND	3	Ground	
S	10	Select Input	
ŌE	8	Output Enable	
HSD1+, HSD2+	5,7		
HSD1-, HSD2-	4,6	Data Port	
D+, D-	1,2		

FUNCTION TABLE

ŌĒ	S	HSD1+, HSD1-	HSD2+, HSD2-
0	0	ON	OFF
0	1	OFF	ON
1	Х	OFF	OFF

X =Don't care



ABSOLUTE MAXIMUM RATINGS (1)

V+ to GND	0V to 6V
Analog, Digital Voltage Range (2)	-0.3 to (V+) + 0.3V
Continuous Current HSDn or Dn	±100mA
Peak Current HSDn or Dn	±150mA
Storage Temperature	−65°C to +150°C
Operating Temperature	−40°C to +85°C
Junction Temperature	+150°C
Package Thermal Resistance @ TA = +	25°C
MSOP-10	204°C/W
QFN-1.4 x1.8-10L	120°C/W
Lead Temperature (Soldering, 10s)	260°C
ESD Susceptibility	
HBM	
MM	200V

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.3V beyond the supply rails should be current-limited to 10mA or less.



ESD SENSITIVITY CAUTION

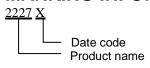
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING	PACKAGE OPTION
RS2227	R\$2227XN	-40°C ~+85°C	MSOP-10	RS2227	Tape and Reel,3000
K52221	RS2227XUTQK10	-40°C ~+85°C	QFN-1.4×1.8-10L	2227X	Tape and Reel,4000

NOTE: X = Date Code

MARKING INFORMATION





ELECTRICAL CHARACTERISTICS

 $(V+=+1.8V \text{ to } +5.5V, \text{ GND} = 0V, \text{ V}_{\text{IH}} = +1.5V, \text{ V}_{\text{IL}} = +0.5V, \text{ T}_{\text{A}} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}.$ Typical values are at V+ = +3.3V, T_A = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS
ANALOG SWITCH							
Analog I/O Voltage (HSD1+, HSD1-, HSD2+, HSD2-)	V _{IS}		-40°C to +85°C	0		V+	V
On Basistanas	Б	$V+ = 3.0V$, $V_{IS} = 0V$ to 0.4V,	+25°C		6	10	
On-Resistance	Ron	I _D = 8mA, Test Circuit 1	-40°C to +85°C			10.5	Ω
On-Resistance Match Between	ΔRon	$V+ = 3.0V$, $V_{IS} = 0V$ to 0.4V,	+25°C		0.15	0.6	Ω
Channels	ΔΚΟΝ	I _D = 8mA, Test Circuit 1	-40°C to +85°C			1.6	Ω
		V+ = 3.0V, V _{IS} = 0V to 1.0V, I _D = 8mA, Test Circuit 1	+25°C		5	7	
On-Resistance Flatness	RFLAT(ON)		-40°C to +85°C			8	Ω
Power Off Leakage Current (D+, D-)	loff	$V+ = 0V, V_D = 0V \text{ to } 3.6 \text{ V}, V_S, V_{\overline{OE}} = 0V \text{ or } 3.6 \text{ V}$	-40°C to +85°C			1	μА
Increase in I+ per Control Voltage	Ісст	V+ = 4.3V, V _S or $V_{\overline{OE}}$ = 2.6 V	-40°C to +85°C			40	μА
Source Off Leakage Current	HSD2(OFF)	V+ = 3.6V, V _{IS} = 3.3V/ 0.3V, V _D = 0.3V/ 3.3V	-40°C to +85°C			1	μА
Channel On Leakage Current	HSD2(ON) HSD1(ON)	$V+ = 3.6V$, $V_{IS} = 3.3V/0.3V$, $V_{D} = 0.3V/3.3V$ or floating	-40°C to +85°C			1	μA
DIGITAL CONTROL INPUTS ⁽¹⁾							
Input High Voltage	V _{IH}		-40°C to +85°C	1.6			V
Input Low Voltage	VıL		-40°C to +85°C			0.5	V
Input Leakage Current	lin	V+ = 3.0V, V _S , $V_{\overline{OE}}$ = 0V or V+	-40°C to +85°C			1	μА

⁽¹⁾ All unused digital inputs of the device must be held at VIO or GND to ensure proper device operation.

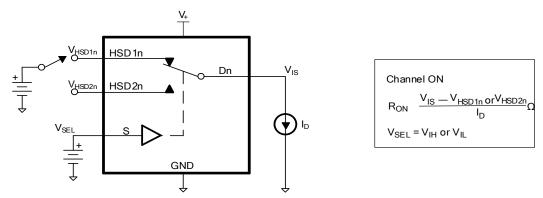


ELECTRICAL CHARACTERISTICS (continued) (V+ = +1.8V to +5.5V, GND = 0V, V_{IH} = +1.5V, V_{IL} = +0.5V, T_A = -40°C to + 85°C. Typical values are at V+ = +3.3V, T_A = +25°C, unless otherwise noted.)

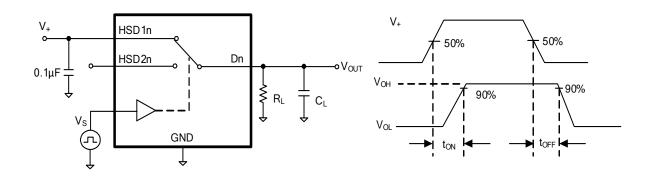
PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS	
DYNAMIC CHARACTERISTICS								
Turn-On Time	ton	$V_{IS} = 0.8V, R_{L} = 50\Omega,$	+25°C		20		ns	
Turn-Off Time	toff	C _L = 10pF, Test Circuit 2	+25°C		15		ns	
Break-Before-Make Time Delay	t _D	V_{IS} = 0.8V, R_L = 50 Ω , C_L = 10pF, Test Circuit 3	+25°C		4		ns	
Propagation Delay	t _{PD}	$R_L = 50\Omega$, $C_L = 10pF$	+25°C		0.35		ns	
Off Isolation	Oıso	Signal = 0dBm, R _L = 50Ω, f = 250MHz, Test Circuit 4	+25°C		-35		dB	
Channel-to-Channel Crosstalk	XTALK	Signal = 0dBm, R_L = 50 Ω , f = 250MHz, Test Circuit 5	+25°C		-40		dB	
-3dB Bandwidth	BW	Signal = 0dBm, R_L = 50 Ω , C_L = 5pF, Test Circuit 6	+25°C		550		MHz	
Channel-to-Channel Skew	tskew	$R_L = 50\Omega$, $C_L = 10pF$	+25°C		0.05		ns	
Charge Injection Select Input to Common I/O	Q	V_G = GND, C_L = 1.0nF, R_G = 0 Ω , Q = C_L x V_{OUT} , Test Circuit 7	+25°C		11		pC	
HSD+, HSD-, D+, D- ON Capacitance	Сом		+25°C		7		pF	
POWER REQUIREMENTS								
Power Supply Range	V+		-40°C to +85°C	1.8		5.5	V	
Power Supply Current	I+	$V + = 3.0V, V_S, V_{\overline{OE}} = 0V \text{ or } V +$	-40°C to +85°C			1	μA	



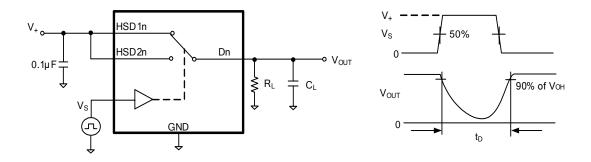
Parameter Measurement Information



Test Circuit 1. ON-State Resistance (Ron)



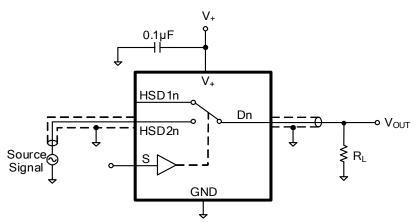
Test Circuit 2. Turn-On (ton) and Turn-Off Time (toff)



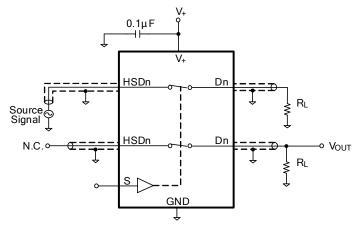
Test Circuit 3. Break-Before-Make Time (t_D)

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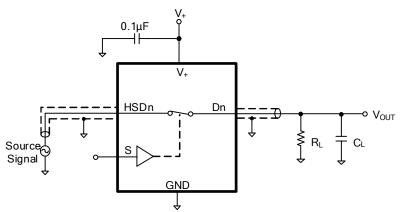


Test Circuit 4.OFF Isolation (O_{ISO})



Channel To Channel Crosstalk= -20 × log $\frac{V_{HSDn}}{V_{OUT}}$

Test Circuit 5. Channel-to-Channel Crosstalk

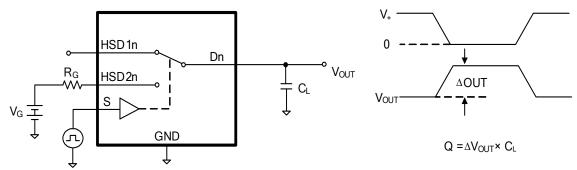


Test Circuit 6. -3dB Bandwidth

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Test Circuit 7. Charge Injection(Q)



APPLICATION NOTES

There are many USB applications in which the USB hubs or controllers have a limited number of USB I/Os. The RS2227 solution can effectively expand the limited USB I/Os by switching between multiple USB buses in order to interface them to a single USB hub or controller. RS2227 can also be used to connect a single controller to two USB connectors or controllers.

Design requirements of the USB 1.0, 1.1, and 2.0 standards should be followed. It is recommended that the digital control pins S and \overline{OE} be pulled up to V+ or down to GND to avoid undesired switch positions that could result from the floating pin.

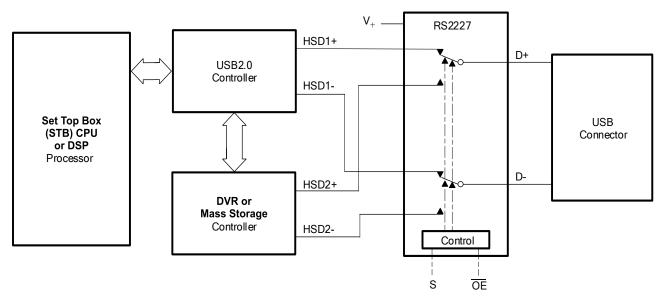
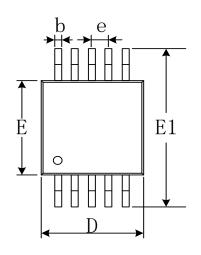
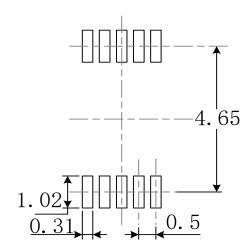


Figure 1. Application Diagram

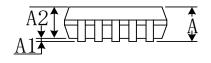


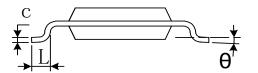
PACKAGE OUTLINE DIMENSIONS MSOP-10





RECOMMENDED LAND PATTERN (Unit: mm)

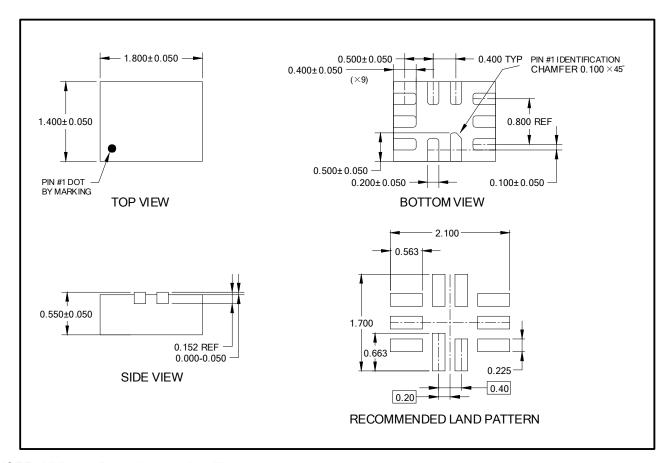




Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
А	0.820	1.100	0.032	0.043	
A1	0.020	0.150	0.001	0.006	
A2	0.750	0.950	0.030	0.037	
b	0.180	0.280	0.007	0.011	
С	0.090	0.230	0.004	0.009	
D	2.900	3.100	0.114	0.122	
е	0.50(0.50(BSC)		(BSC)	
E	2.900	3.100	0.114	0.122	
E1	4.750	5.050	0.187	0.199	
L	0.400	0.800	0.016	0.031	
θ	0°	6°	0°	6°	



PACKAGE OUTLINE DIMENSIONS $QFN-1.4\times1.8-10L$



NOTE: All linear dimensions are in millimeters.